

Semiconductor Equipment Corporation

Aquabond Adhesives and Cleaning Agents



SAFE, HIGH PERFORMANCE WATER SOLUBLE ADHESIVES AND CLEANING AGENTS

Today there is more pressure to develop process without the use of chemicals. We can help you with our unique line of water soluble adhesives. Whether you are bonding quartz, fused silica, Bk7, garnet, sapphire, ceramics or other single crystal hard materials, we have the right temporary adhesive at the right bonding temperature for your process.

Aquabond Adhesives offer numerous benefits such as:

Easy Removal

Debonding of parts after cutting or machining is accomplished using hot water and an Aquaclean water based cleaning agent, often accompanied by ultrasonic or air irrigation. The use of acetone or aggressive solvents and their attendant health, fire and environmental hazards is eliminated.

No Waste Requirements

With proper approvals, the spent cleaning solution can be sewer discharged. The Aquabond adhesive system is unique in this respect.



Improved Quality and Yields

High hardness and shear strength improves precision machining operations creating less attrition.

Environmentally Friendly and Cost Effective

Following a simple debonding process using the aqueous cleaning agent, you will find your parts are much cleaner than using a typical thermoplastic stick followed by the solvent cleaning approach. Not only is the adhesive residue removed, but also oils and particles left by other areas of your process. Afterward, the cleaning solution can simply be poured down the drain. It does not need to be collected and further dealt with as hazardous waste.

	Aquabond 55	Aquabond 65	Aquabond 85
Color:	Purple	Orange	Green
Penetration @ 25C:	5	5	<5
Tacking Temperature C:	40-55	40-55	50-60
Softening Temperature C:	45-50	55-60	60-85
Melting Temperature C:	50-55	60-65	85-105
Bonding Temperature C:	90-110	90-110	85-150
Viscosity - cps:	<1000 @ 75C	<3000 @ 75C	<3000 @ 75C
Cooling Time @ 25C, in hr.:	0.5	0.5	0.5
Water Solubility @ 25C, %:	<0.1	<0.1	<0.1
Water Solubility @ 80C, %:	100	100	100
Debond/Cleanup**	Hot DI Water and Aquaclean 900		

*Use of ultrasonic or injected air cleaning speeds debonding in all systems



Order your sample kit today:

- 1 stick of Aquabond 55
- 1 stick of Aquabond 65
- 1 stick of Aquabond 85
- 1 lb container of Aquaclean 900
- MSDS
- Application Bulletins & Technical Data Sheet

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